

Title (en)

Water-soluble copper, copper alloys and non-ferrous metals intermediate cold and hot rolling composition

Title (de)

Wasserlösliche Zusammensetzung für Kalt- und Warmwalzen von Kupfer, Kupferlegierungen und Nichteisen-Metalzwischenprodukten

Title (fr)

Composition soluble dans l'eau pour le laminage à froid et à chaud de cuivre, d'alliages de cuivre et de produits intermédiaires non-ferreux

Publication

EP 1123971 A1 20010816 (EN)

Application

EP 00400348 A 20000208

Priority

EP 00400348 A 20000208

Abstract (en)

The present invention relates to a water-soluble copper, copper alloys and non-ferrous metals intermediate cold and hot rolling composition comprising a base stock oil and, based on the total weight of the composition : from 1 to 80% by weight of a combination of a monoester of a fatty acid with a polyol and a tetraester of a fatty acid with pentaerythritol; the weight monoester : tetraester ratio of said combination ranging from 1:20 to 10:1; and from 0.02 to 2% by weight of an azole derivative. The invention also relates to an oil-in-water emulsion, an intermediate cold rolling process, a hot rolling process and the use of the oil-in-water emulsion in an intermediate cold or hot rolling process. <IMAGE>

IPC 1-7

C10M 173/00; **C10M 169/04**

IPC 8 full level

B21B 45/02 (2006.01); **C10M 101/02** (2006.01); **C10M 125/14** (2006.01); **C10M 129/10** (2006.01); **C10M 129/16** (2006.01); **C10M 129/42** (2006.01); **C10M 129/74** (2006.01); **C10M 129/76** (2006.01); **C10M 133/08** (2006.01); **C10M 133/38** (2006.01); **C10M 133/44** (2006.01); **C10M 133/46** (2006.01); **C10M 135/10** (2006.01); **C10M 135/32** (2006.01); **C10M 135/36** (2006.01); **C10M 137/04** (2006.01); **C10M 155/02** (2006.01); **C10M 159/04** (2006.01); **C10M 169/04** (2006.01); **C10M 173/00** (2006.01); **C10N 20/02** (2006.01); **C10N 30/00** (2006.01); **C10N 40/24** (2006.01)

CPC (source: EP US)

C10M 141/06 (2013.01 - EP US); **C10M 141/12** (2013.01 - EP US); **C10M 173/00** (2013.01 - EP US); **C10M 2201/105** (2013.01 - EP US); **C10M 2203/1065** (2013.01 - EP US); **C10M 2207/026** (2013.01 - EP US); **C10M 2207/126** (2013.01 - EP US); **C10M 2207/283** (2013.01 - EP US); **C10M 2207/289** (2013.01 - EP US); **C10M 2209/104** (2013.01 - EP US); **C10M 2215/042** (2013.01 - EP US); **C10M 2215/223** (2013.01 - EP US); **C10M 2223/04** (2013.01 - EP US); **C10M 2229/02** (2013.01 - EP US); **C10N 2030/02** (2013.01 - EP US); **C10N 2030/12** (2013.01 - EP US); **C10N 2030/24** (2020.05 - EP US); **C10N 2040/24** (2013.01 - EP US)

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EP2788461A4

Designated contracting state (EPC)

FR

DOCDB simple family (publication)

EP 1123971 A1 20010816; AT E278753 T1 20041015; AU 2001233748 B2 20041223; AU 3374801 A 20010820; BR 0108159 A 20030121; CA 2397879 A1 20010816; CN 1395612 A 20030205; DE 60106208 D1 20041111; DE 60106208 T2 20060216; EP 1257624 A1 20021120; EP 1257624 B1 20041006; JP 2003522282 A 20030722; US 2006142167 A1 20060629; WO 0159046 A1 20010816

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EP 00400348 A 20000208; AT 01905750 T 20010207; AU 2001233748 A 20010207; AU 3374801 A 20010207; BR 0108159 A 20010207; CA 2397879 A 20010207; CN 01803780 A 20010207; DE 60106208 T 20010207; EP 0101381 W 20010207; EP 01905750 A 20010207; JP 2001558186 A 20010207; US 18249302 A 20021115